

Silicon Diffused Power Transistor**BU2525DF****GENERAL DESCRIPTION**

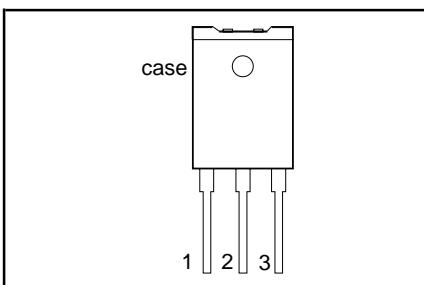
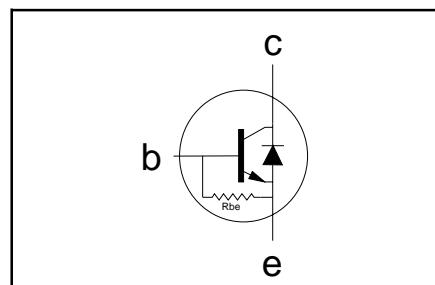
New generation, high-voltage, high-speed switching npn transistor with integrated damper diode in a plastic full-pack envelope intended for use in horizontal deflection circuits of large screen colour television receivers up to 32 kHz.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	1500	V
V_{CEO}	Collector-emitter voltage (open base)		-	800	V
I_C	Collector current (DC)		-	12	A
I_{CM}	Collector current peak value		-	30	A
P_{tot}	Total power dissipation		-	45	W
V_{CEsat}	Collector-emitter saturation voltage	$T_{hs} \leq 25^\circ\text{C}$ $I_C = 8.0 \text{ A}; I_B = 1.6 \text{ A}$	-	5.0	V
I_{Csat}	Collector saturation current		8.0	-	A
t_s	Storage time	$I_{Csat} = 8.0 \text{ A}; I_{B(end)} = 1.1 \text{ A}$	3.0	4.0	μs

PINNING - SOT199

PIN	DESCRIPTION
1	base
2	collector
3	emitter
case	isolated

PIN CONFIGURATION**SYMBOL****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	1500	V
V_{CEO}	Collector-emitter voltage (open base)		-	800	V
I_C	Collector current (DC)		-	12	A
I_{CM}	Collector current peak value		-	30	A
I_B	Base current (DC)		-	8	A
I_{BM}	Base current peak value		-	12	A
$-I_{B(AV)}$	Reverse base current	average over any 20 ms period	-	200	mA
$-I_{BM}$	Reverse base current peak value ¹		-	9	A
P_{tot}	Total power dissipation		-	45	W
T_{stg}	Storage temperature	$T_{hs} \leq 25^\circ\text{C}$	-65	150	°C
T_j	Junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$R_{th(j-hs)}$	Junction to heatsink	without heatsink compound	-	3.7	K/W
$R_{th(j-hs)}$	Junction to heatsink	with heatsink compound	-	2.8	K/W
$R_{th(j-a)}$	Junction to ambient	in free air	35	-	K/W

¹ Turn-off current.

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ISOLATION LIMITING VALUE & CHARACTERISTIC $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	Repetitive peak voltage from all three terminals to external heatsink	R.H. $\leq 65\%$; clean and dustfree	-		2500	V
C_{isol}	Capacitance from T2 to external heatsink	$f = 1\text{ MHz}$	-	22	-	pF

STATIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CES}	Collector cut-off current ²	$V_{BE} = 0\text{ V}; V_{CE} = V_{CESMmax}$	-	-	1.0	mA
I_{CES}		$V_{BE} = 0\text{ V}; V_{CE} = V_{CESMmax}$	-	-	2.0	mA
I_{EBO}	Emitter cut-off current	$T_j = 125^\circ\text{C}$	72	110	218	mA
R_{eb}	Base-emitter resistance	$V_{EB} = 6.0\text{ V}; I_c = 0\text{ A}$	-	55	-	Ω
BV_{EBO}	Emitter-base breakdown voltage	$V_{EB} = 6.0\text{ V}$	7.5	13.5	-	V
$V_{CEO}sust$	Collector-emitter sustaining voltage	$I_B = 600\text{ mA}$	800	-	-	V
V_{CEsat}	Collector-emitter saturation voltage	$I_B = 0\text{ A}; I_c = 100\text{ mA}$	-	-	5.0	V
V_{BEsat}	Base-emitter saturation voltage	$L = 25\text{ mH}$	-	-	1.1	V
h_{FE}	DC current gain	$I_c = 8.0\text{ A}; I_B = 1.6\text{ A}$	-	11	-	
h_{FE}		$I_c = 8.0\text{ A}; I_B = 1.6\text{ A}$	-	7	9.5	
V_F	Diode forward voltage	$I_c = 1\text{ A}; V_{CE} = 5\text{ V}$	5	7	2.0	V
		$I_c = 8\text{ A}; V_{CE} = 5\text{ V}$	-	1.6	-	
		$I_F = 8\text{ A}$	-	-	-	

DYNAMIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
C_c	Collector capacitance	$I_E = 0\text{ A}; V_{CB} = 10\text{ V}; f = 1\text{ MHz}$	145	-	pF
t_s	Switching times (32 kHz line deflection circuit)	$I_{Csat} = 8.0\text{ A}; L_C = 260\text{ }\mu\text{H}; C_{fb} = 13\text{ nF}; I_{B(end)} = 1.1\text{ A}; L_B = 2.5\text{ }\mu\text{H}; -V_{BB} = 4\text{ V}; (-dI_B/dt) = 1.6\text{ A}/\mu\text{s}$	3.0	4.0	μs
t_f	Turn-off storage time Turn-off fall time		0.2	0.35	μs
V_{fr}	Anti-parallel diode forward recovery voltage	$I_F = 8\text{ A}; dI_F/dt = 50\text{ A}/\mu\text{s}$	16	-	V
t_{fr}	Anti-parallel diode forward recovery time	$V_F = 5\text{ V}$	410	-	ns

² Measured with half sine-wave voltage (curve tracer).

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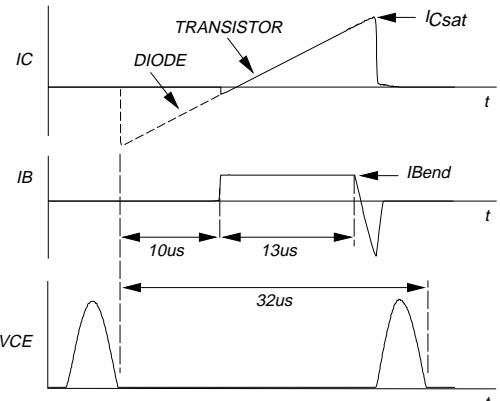


Fig.1. Switching times waveforms.

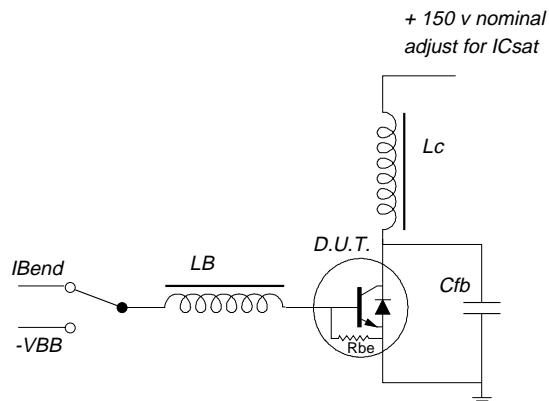


Fig.4. Switching times test circuit.

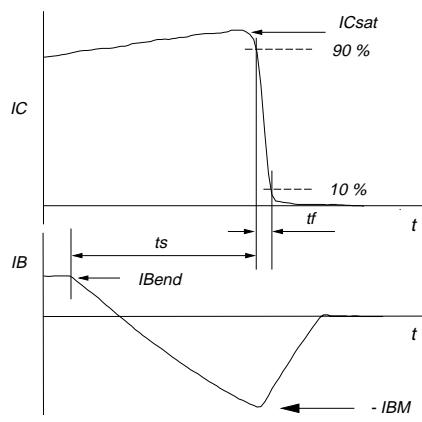
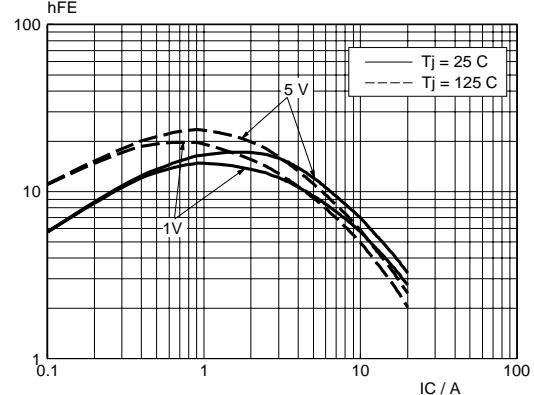
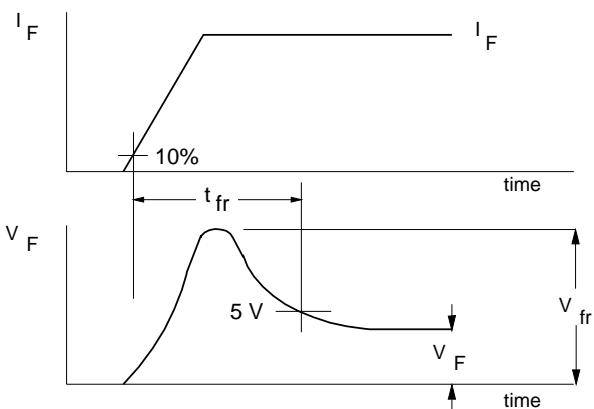
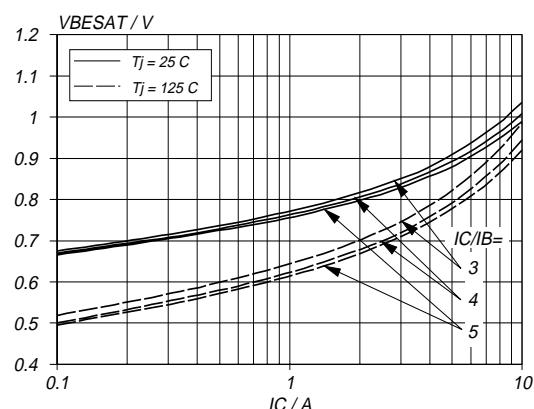
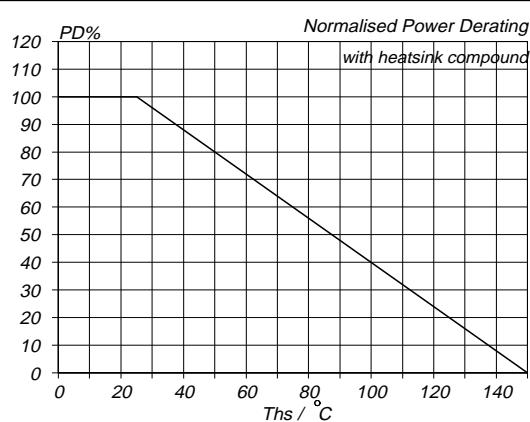
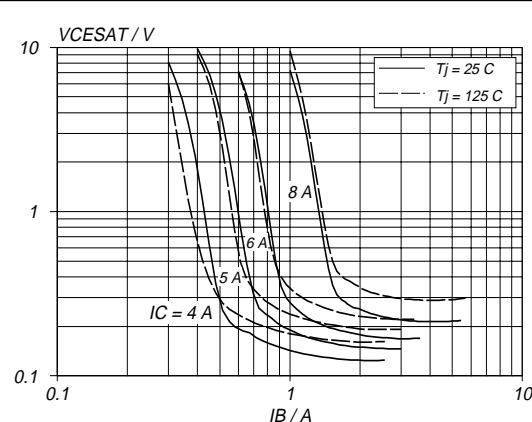
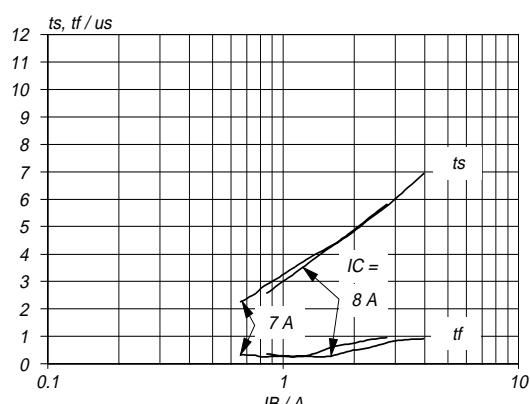
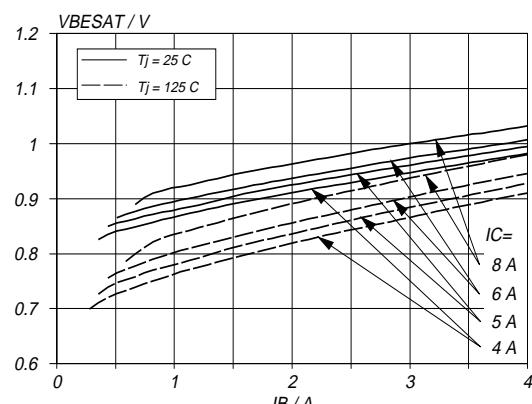
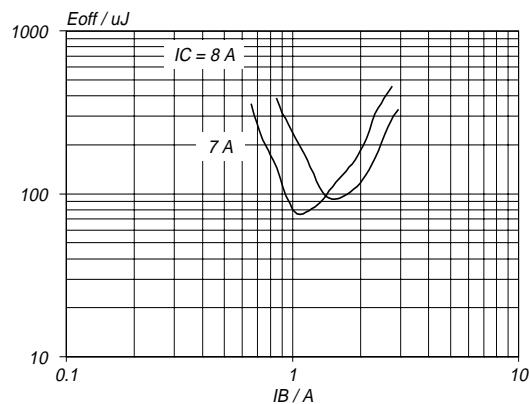
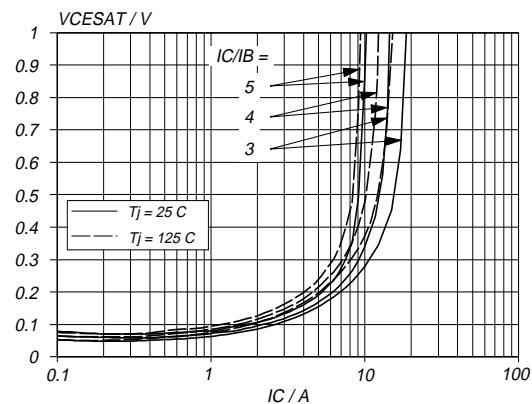


Fig.2. Switching times definitions.

Fig.5. Typical DC current gain. $h_{FE} = f (I_C)$ parameter V_{CE} Fig.3. Definition of anti-parallel diode V_{fr} and t_{fr} Fig.6. Typical base-emitter saturation voltage. $V_{BEsat} = f (I_C)$; parameter I_C/I_B

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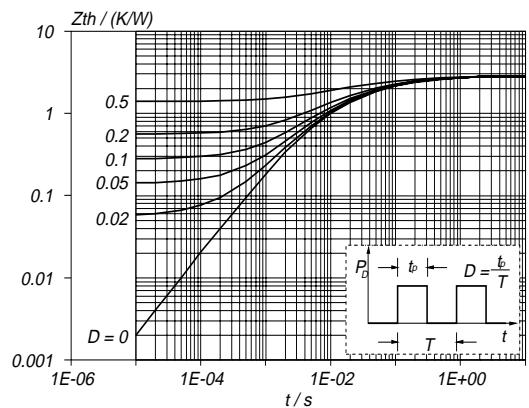


Fig. 13. Transient thermal impedance.
 $Z_{th(j-hs)} = f(t)$; parameter $D = t_p/T$

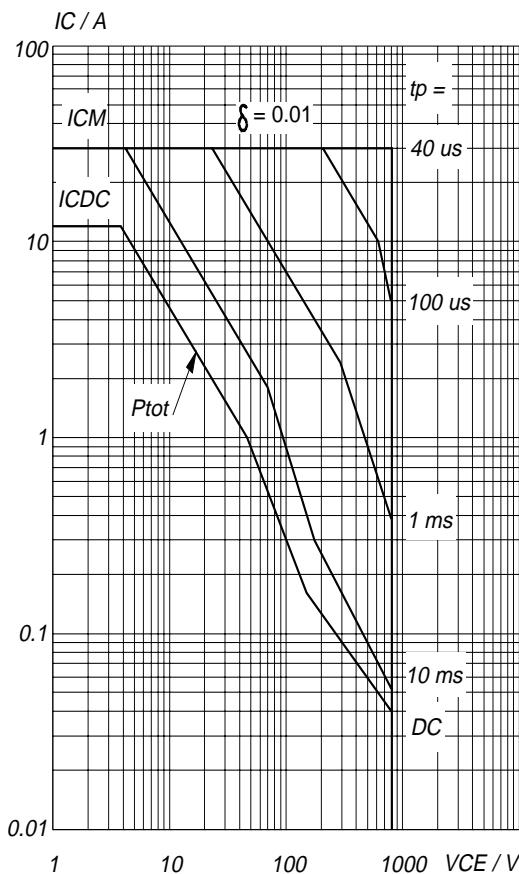


Fig. 14. Forward bias safe operating area. $T_{hs} = 25^\circ\text{C}$
 I_{CDC} & $I_{CM} = f(V_{CE})$; I_{CM} single pulse; parameter t_p .
Second-breakdown limits independant of temperature.
Mounted with heatsink compound.

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MECHANICAL DATA

Dimensions in mm

Net Mass: 5.5 g

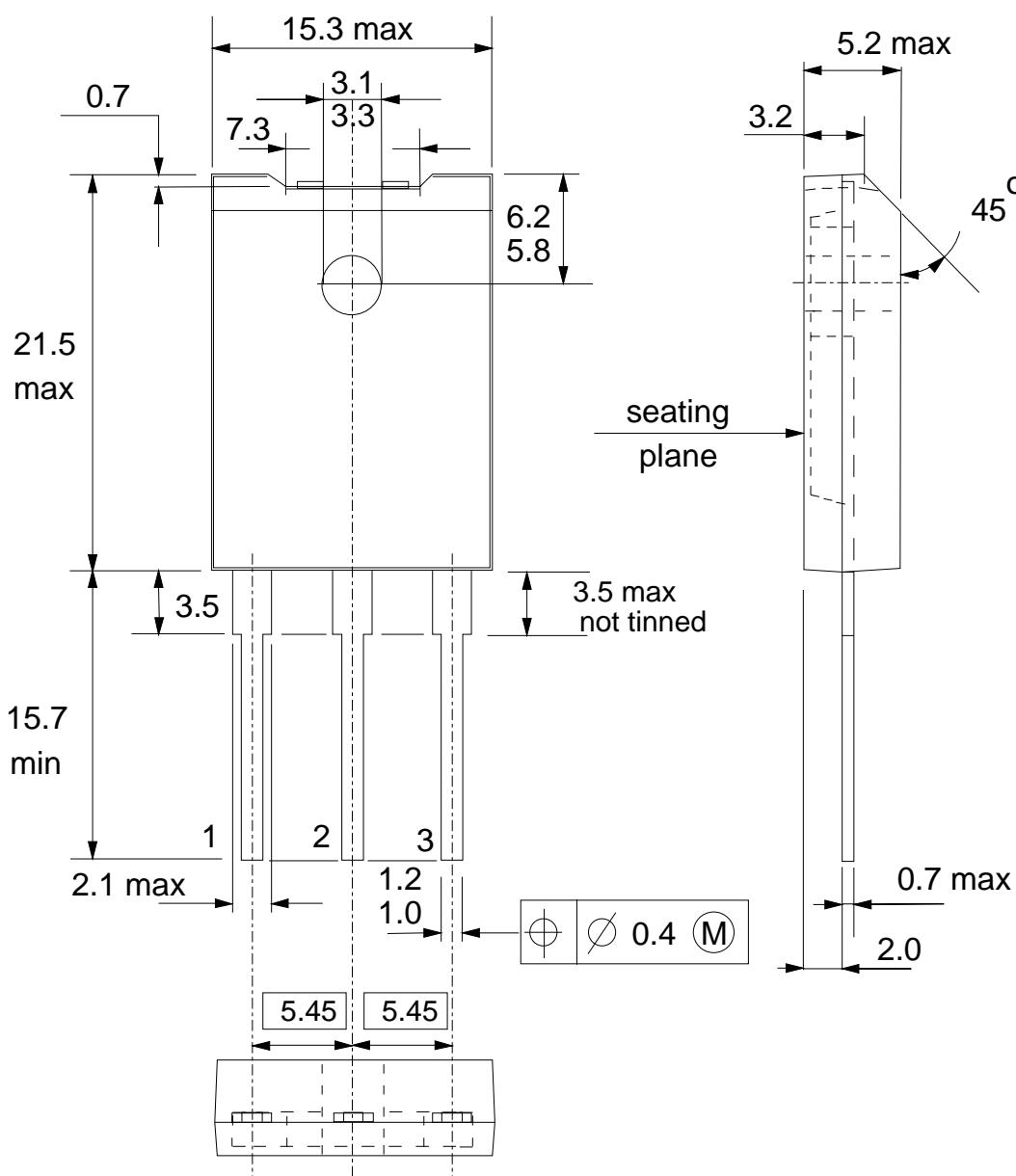


Fig.15. SOT199; The seating plane is electrically isolated from all terminals.

Notes

1. Refer to mounting instructions for F-pack envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Silicon Diffused Power Transistor**BU2525DF****DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	
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